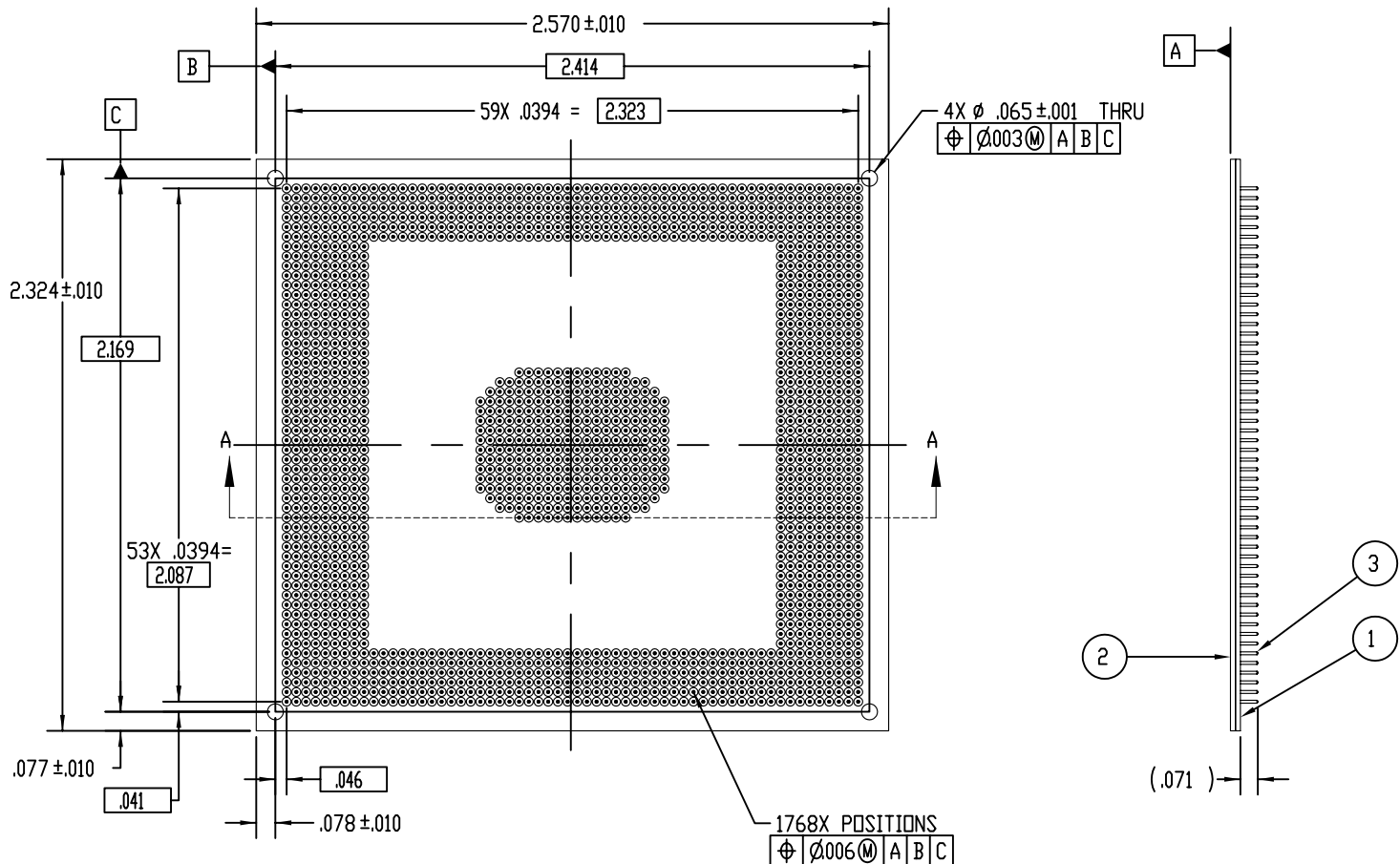


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	05/16/07	H.N.
B	ADDED PACKAGE SPECIFICATIONS	06/01/07	H.N.

F7975



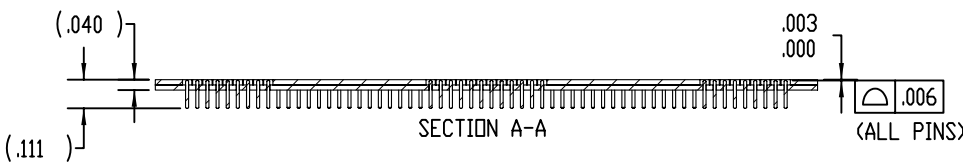
- NOTES:
- INSULATOR MATERIAL: FR4, BLACK.
 - PIN MATERIAL: PHOSPHOR BRONZE.
PIN PLATING: HARD GOLD OVER NICKEL.
 - REFER TO ET HI₆ APPLICATION GUIDELINES FOR LAND PATTERN, STENCIL DESIGN, AND KEEP OUT ZONE RECOMMENDATIONS.

RoHS Compliant

PACKAGE SPECIFICATIONS	
PIN COUNT	≡ 1768
LEAD PITCH	≡ 1.00mm
GRID SIZE	≡ 54X60
PACKAGE SIZE	≡ 58.00X64.00mm

Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
TEL:(408)982-0660 FAX:(408)982-0664



UNLESS OTHERWISE SPECIFIED	
DIMENSIONS ARE: IN INCHES (MILLIMETERS)	
TOLERANCES ARE:	
DECIMALS:	ANGLES: ± 10°
.01 ± .001	.015 ± .005
.001 ± .0005	FRACTIONS: ± 1/64
.000 ± .0005	
.000 ± .0005	
.000 ± .0005	



SHEET: 1 OF 1	DATE: 05/16/07	REVISION: B	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: HLP-001768-B-10	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: HLP-001768-B-10	